Specification of Thermoelectric Module

TETS1-12730

Description

The 127 couples, 25 mm × 25 mm size single module is made of selected high performance ingot and fabricated by our unique "soft" processes to achieve superior cooling/heating performance. The module is able to run million thermal cycles in 70 °C temperature change range with less 3% degrading. It is good for the need of frequently cooling and heating applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance
- Sustain million thermal cycles with 70 °C temperature change range

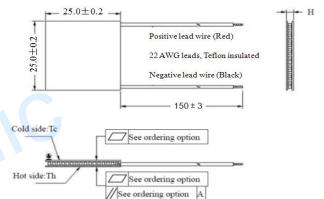
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	72	81	Temperature Difference between cold and hot side of the module	
			when cooling capacity is zero at cold side	
U _{max} (Voltage)	16.4	17.2	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	3.0	3.0	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	30.6	33.9	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	4.1	4.4	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

- 1. T100: BiSn (Tmelt=138°C)
- 2. T200: CuSn (Tmelt = 227 °C)
- **B. Sealant:**
- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

C. Ceramics:

- 1. Alumina (Al₂O₃, white 96%)
- 2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

- 1. Blank ceramics (not metallized)
- 2. Metallized

Ordering Option

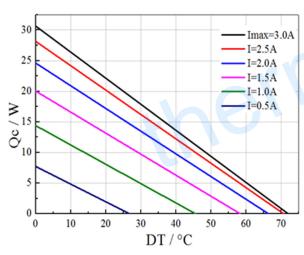
Suffix	Thickness H / (mm)	Flatness/ Parallelism (mm)	Lead wire length (mm) Standard/Optional length
TF	0:3.0±0.1	0:0.05/0.05	150±3/Specify
TF	1:3.0±0.05	1:0.03/0.03	150±3/Specify

Operation Cautions

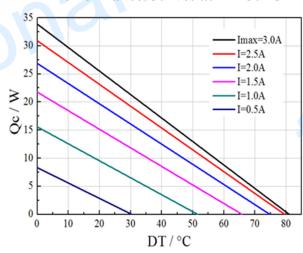
- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- ullet Operation below I_{max} or V_{max}
- •Work under DC

Performance Curve

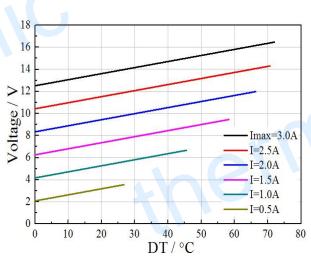


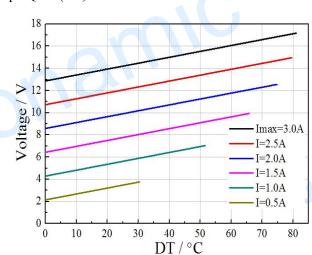


Performance Curves at Th=50 °C

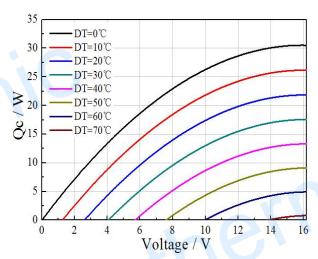


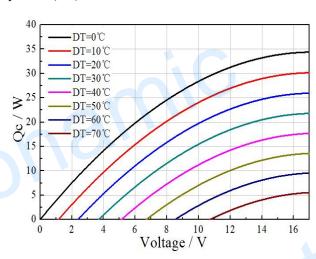
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V = f(DT)

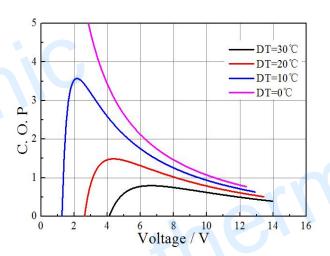


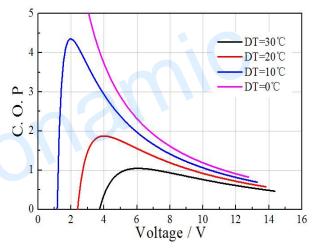


Standard Performance Graph Qc = f(V)

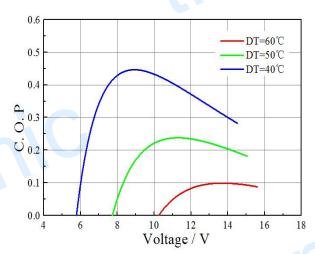


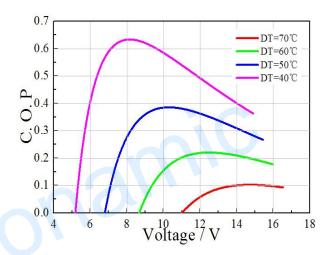
Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



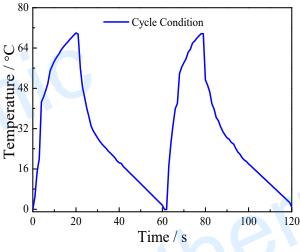


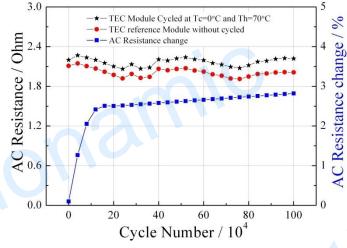
Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

A typical 127 couples module is fabricated by the unique "soft" process and has demonstrated that it only has less than 3% degrading after 1000,000 thermal cycling. The below graphic shows that in beginning 500,000 cycles, it degrade about 2.5%, and then go on stable with very tiny degrading in further 500,000 thermal cycles. It is derived out that the modules can go over million thermal cycles.

TEC Thermal Cycle Lifetime Test On TETC1-12706





Typical cooling-heating cycle

The Chart for AC Resistance and AC Resistance Changes
vs. Cycle Number